

## Technical Data Sheet

# EtroX<sup>®</sup> V - ASTM

PEEK

### Typical industries

- Electronics
- Semiconductor Industry
- Clean-Room Technology
- Mechanical Engineering Industry
- Semiconductor CMP
- Semiconductor High and low temperature
- Semiconductor Back-End applications

	Test method	Unit	Guideline value
<b>General properties</b>			
Moisture	ASTM D6980	%	0.11
<b>Mechanical properties</b>			
Tensile Strength	ASTM D638	psi	14320
Tensile Modulus	ASTM D638	ksi	765
Elongation at Break	ASTM D638	%	3.5
Flexural Strength	ASTM D790	psi	23214
Flexural Modulus	ASTM D790	ksi	791
<b>Thermal properties</b>			
Heat Deflection Temperature	ASTM D648 @ 264psi and 2C/min	°C	>205

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